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(71) Applicant *(for all designated States except US)*: **ELECTRO SCIENTIFIC INDUSTRIES, INC.** [US/US]; 13900 NW Science Park Drive, Portland, Oregon 97229-5497 (US).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **O'BRIEN, James N.** [US/US]; 912 NE Revere Avenue, Unit 1, Bend, Oregon 97701 (US). **PIROGOVSKY, Peter** [US/US]; 8815 SW 45th Drive, Portland, Oregon 97219 (US).

(74) Agent: **BARKER, Aaron D.**; One Utah Center, 201 So. Main Street, Suite 1100, Salt Lake City, Utah 84111 (US).

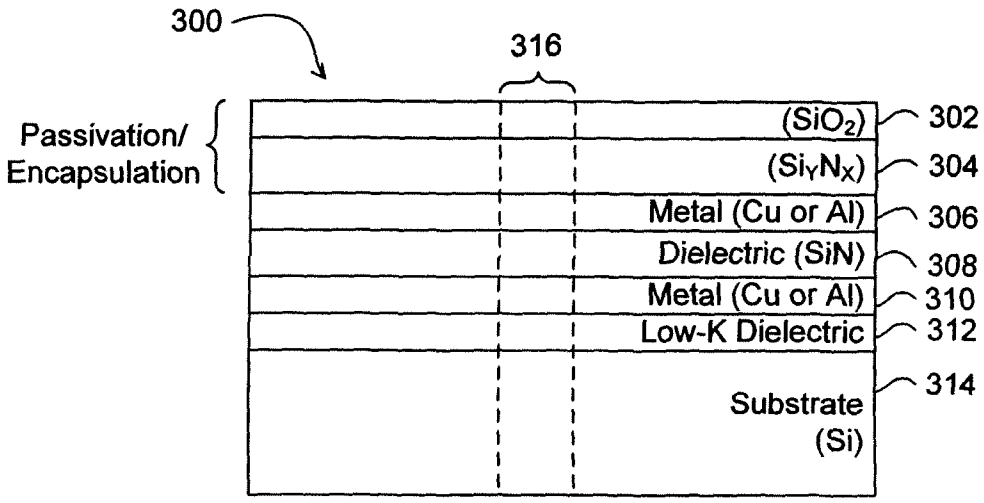
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(54) **Title:** INFRARED LASER WAFER SCRIBING USING SHORT PULSES



(57) **Abstract:** Systems and methods are provided for scribing wafers (300) to efficiently ablate passivation and/or encapsulation layers (302, 304) while reducing or eliminating chipping and cracking in the passivation and/or encapsulation layers (302, 304). Short laser pulses are used to provide high peak powers and reduce the ablation threshold. In one embodiment, the scribing is performed by a q-switched CO_2 laser.

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